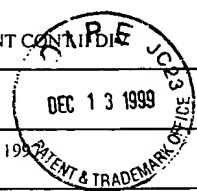
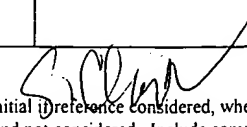
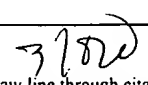
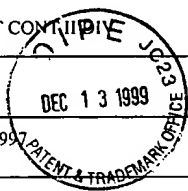
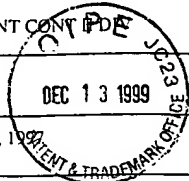
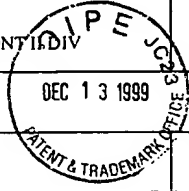
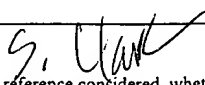
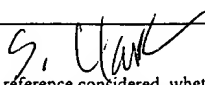
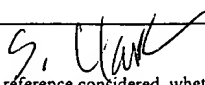





FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant <i>Khandros, et al.</i>			
				Filing Date: December 3, 1999			
U.S. PATENT DOCUMENTS							
*EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
SK	AA	4,961,105	10/2/90	<i>Yamamoto</i>	357	72	
SK	AB	5,216,278	6/1/93	<i>Lin et al</i>	257	688	
SN	AC	5,241,133	8/31/93	<i>Mullen, III et al.</i>	174	52.4	
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
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	AK						
FOREIGN PATENT DOCUMENTS							
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SK	AL JP 63-290796	11/28/88	Japan			X	
SK	AM JP 63-51196	3/4/88	Japan			X	
SK	AN JP 63-290795	11/28/88	Japan			X	
SK	AO JP 2-128453	5/16/90	Japan			X	
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
SK	AR	JP 63-290796, copy including annotations					
SK	AS	JP 63-51196, copy including annotations					
SN	AT	JP 63-290795, copy including annotations					
EXAMINER				DATE CONSIDERED			
							
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							

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	AL							
	AM							
	AN							
	AO							
	AP							
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)								
gk	✓	AR	JP 2-128453, copy including annotations					
gk	✓	AS	1987 Proceedings 37 th Electronic Components Conference, May 11-13, 1987, Die Attachment Design and Its Influence on Thermal Stresses in the Die and the Attachment, E. Suhir, pages 508-517					
gk	✓	AT	Electronic Components Conference 33 rd , May 16-18, 1983, The Quality of Die-Attachment and Its Relationship to Stresses and Vertical Die-Cracking, C.G.M. van Kessel, S.A. Gee and J.J. Murphy, pages 237-244					
EXAMINER				DATE CONSIDERED				
S. Clark				3/80				
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				Filing Date: December 3, 1997			
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FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO
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	AN						
	AO						
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
SVC	✓ AR	Electronic Components Conference 34 th , May 14-16, 1984, Die Attach in Hi-Rel P-Dips: Polyimides or Low Chloride Epoxies?, Justin C. Bolger and Charles T. Mooney, pages 63-67					
SVC	✓ AS	Ablebond® 84-3 MV, Electrically Insulating Epoxy Adhesive, 12/97					
SVC	✓ AT	Ablebond® 84-3 MV, One Component, Insulative Chip Adhesive, 11/97					
EXAMINER <i>S. Clark</i>				DATE CONSIDERED <i>3/00</i>			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT CONT DIV		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant Khandros, et al.			
				Filing Date: December 3, 1997			
U.S. PATENT DOCUMENTS							
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FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
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AL							
AM							
AN							
AO							
AP							
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
SK	✓ AR	Ablebond® 84-3MV, Electrically Insulating Chip Adhesive, Rev. 6/90					
SK	✓ AS	Ablestik®, One Component, Insulating Chip Adhesive, Rev. 2/88					
SK	✓ AT	Microelectronics Packaging Handbook. Rao R. Tummala, Eugene J. Rymaszewski, pages 312-320, (1989).					
EXAMINER		DATE CONSIDERED					
							
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							

FORM PTO-1449 (Rev. 7-80)		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. TESSERA 3.3-018 CONT CONT II DIV		Application No. 08/984,615	
LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)				Applicant Khandros, et al.			
				Filing Date: December 3, 1997		Group 2815	
U.S. PATENT DOCUMENTS							
EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
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FOREIGN PATENT DOCUMENTS							
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	AL						
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	AN						
	AO						
	AP						
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
	AR	"No Stress" Dielectric Epoxy Adhesives with High Thermal Conductivity, date unknown.					
	AS						
	AT						
EXAMINER 				DATE CONSIDERED 3/00			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							
232729_1.DOC							